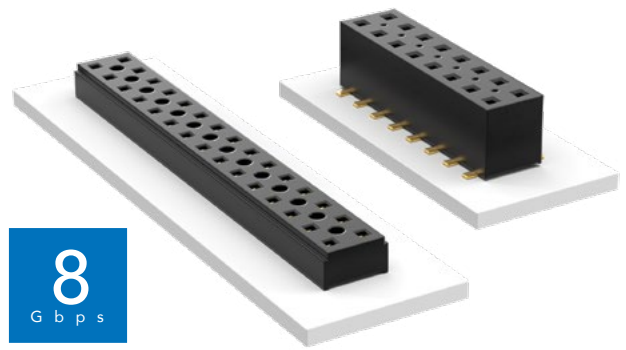


COST-EFFECTIVE & DUAL WIPE SOCKETS

(2.00 mm) .0787" PITCH • TLE/CLT SERIES



TLE

Mates:

TMMH, TMM, MTMM,
MMT, TW, LTMM, ZLTMM,
TCMD, TSH

CLT

Mates:

TMM, TMMH, MTMM,
MMT, TW, TSH

SPECIFICATIONS

TLE

Insulator Material:

Black Liquid Crystal Polymer

Contact Material:

Phosphor Bronze

Plating:

Au over 50 μ " (1.27 μ m) Ni

Current Rating (TLE/TMMH):

3.2 A per pin

(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Insertion Depth:

(2.08 mm) .082" to

(4.37 mm) .172" with

(0.38 mm) .015" wipe,

pass-through, or

(3.35 mm) .132" min

for bottom entry

CLT

Same as TLE except:

Plating:

Sn or Au over 50 μ " (1.27 μ m) Ni

Current Rating (TMMH/CLT):

4.1 A per pin

(2 pins powered)

Insertion Depth:

Top Entry=

(1.40 mm) .055" minimum

Bottom Entry=

(2.57 mm) .101" minimum

(add board thickness for

correct post OAL)

Max Cycles:

100 with 10 μ " (0.25 μ m) Au

PROCESSING

TLE

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-26)

(0.15 mm) .006" max (27-50)*

*(.004" stencil solution

may be available; contact

ipg@samtec.com)

CLT

Same as TLE except:

SMT Lead Coplanarity:

(0.10 mm) .004" max (02-25)

(0.15 mm) .006" max (26-34)*

(0.20 mm) .008" max (35-50)*

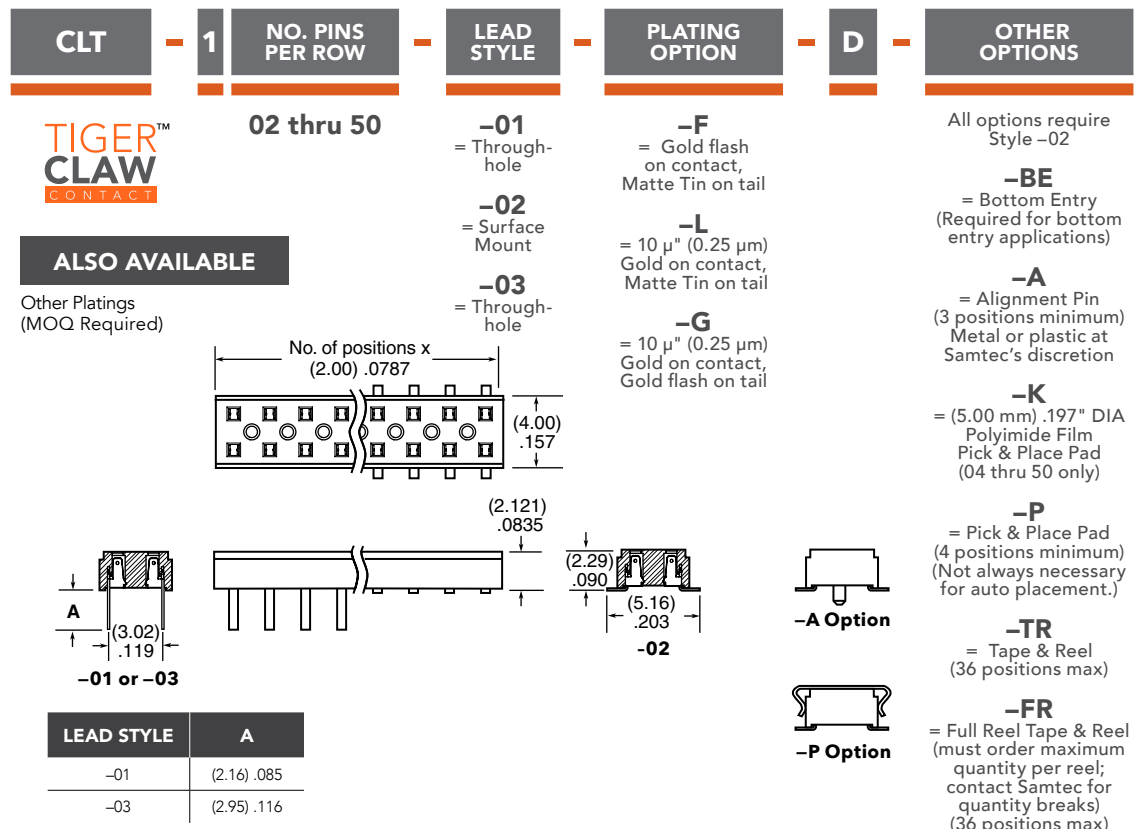
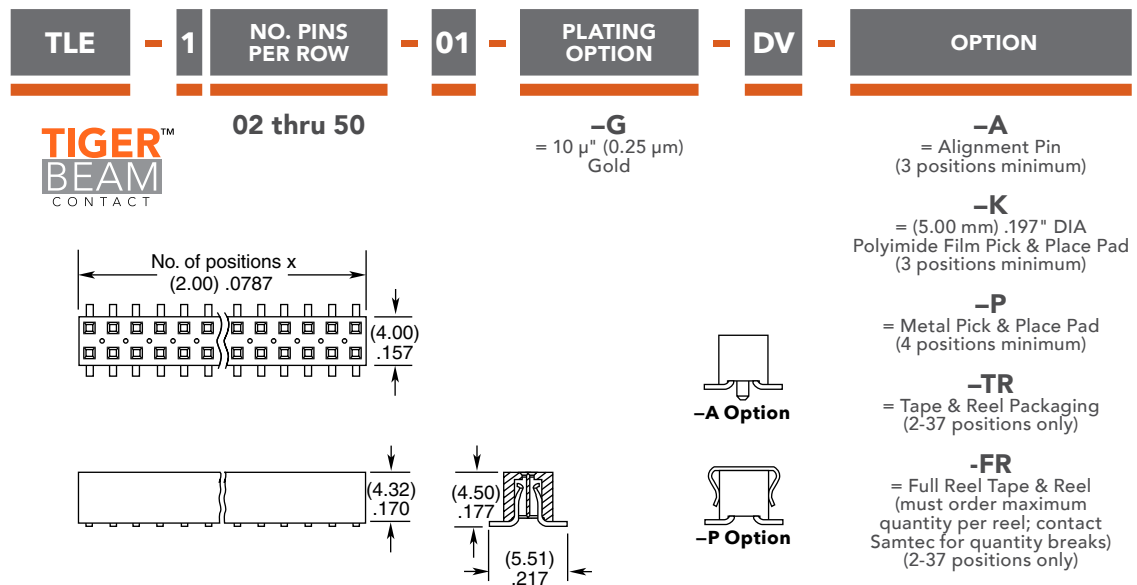
*(.004" stencil solution

may be available; contact

ipg@samtec.com)

Note:

Some lengths, styles and
options are non-standard,
non-returnable.



ALSO AVAILABLE

Other Platings
(MOQ Required)

LEAD STYLE	A
-01	(2.16) .085
-03	(2.95) .116